Zytel® HTNFE150061 BK900 (PRELIMINARY)

HIGH PERFORMANCE POLYAMIDE RESIN

Zytel® HTNFE150061 BK900 is a 50% carbon/glass reinforced, heat stabilized high performance polyamide resin. It is also a PPA resin.

Product information

Resin Identification	PPA-(CF+GF)50	ISO 1043
Part Marking Code	>PPA-(CF+GF)50<	ISO 11469
Part Marking Code	>PPA-(CF+GF)50<	SAE J1344
ISO designation	ISO 16396-PA*,(CF+GF),M1CGHR,S10-250	

Rheological properties

	dry/cond.		
Molding shrinkage, parallel	0.1 / -	%	ISO 294-4, 2577
Molding shrinkage, normal	0.2 / -	%	ISO 294-4, 2577

Typical mechanical properties

	dry/cond.		
Tensile modulus	5.37E6 / -	psi	ISO 527-1/-2
Tensile stress at break, 5mm/min	43500 / -	psi	ISO 527-1/-2
Tensile strain at break, 5mm/min	1.2 / -	%	ISO 527-1/-2
Flexural modulus	4.57E6 / -	psi	ISO 178
Flexural strength	65300 / -	psi	ISO 178
Charpy impact strength, 23°C	27.1 / -	ftlb/in²	ISO 179/1eU
Charpy notched impact strength, 23°C	3.81 / -	ftlb/in²	ISO 179/1eA

Thermal properties

	dry/cond.		
Melting temperature, first heat	577 / *	°F	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	509 / *	°F	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	0.02 / *	E-4/°F	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), parallel, -40-23°C	0.0111 / *	E-4/°F	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), parallel, 55-160°C	0.0167 / *	E-4/°F	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	0.261 / *	E-4/°F	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal, -40-23°C	0.228 / *	E-4/°F	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal, 55-160°C	0.456 / *	E-4/°F	ISO 11359-1/-2

Electrical properties

	dry/cond.		
Volume resistivity, conductive plastics	0.01 / -	Ohm.m	ASTM D 4496

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Physical/Other properties

	dry/cond.		
Water absorption, Immersion 24h	0.4 / *	%	Sim. to ISO 62
Density	0.0516 / -	lb/in³	ISO 1183

Injection

Drying Recommended	yes	
Drying Temperature	230	°F
Drying Time, Dehumidified Dryer	6 - 8	h
Processing Moisture Content	≤0.1	%
Min. melt temperature	590	°F
Max. melt temperature	617	°F
Min. mold temperature	203	°F
Max. mold temperature	266	°F
Hold Pressure Time (h is the max. wall thickness of the part in mm)	h²+2	s

Characteristics

Processing	Injection Molding
Additives	Release agent
Special characteristics	Heat stabilized or stable to heat

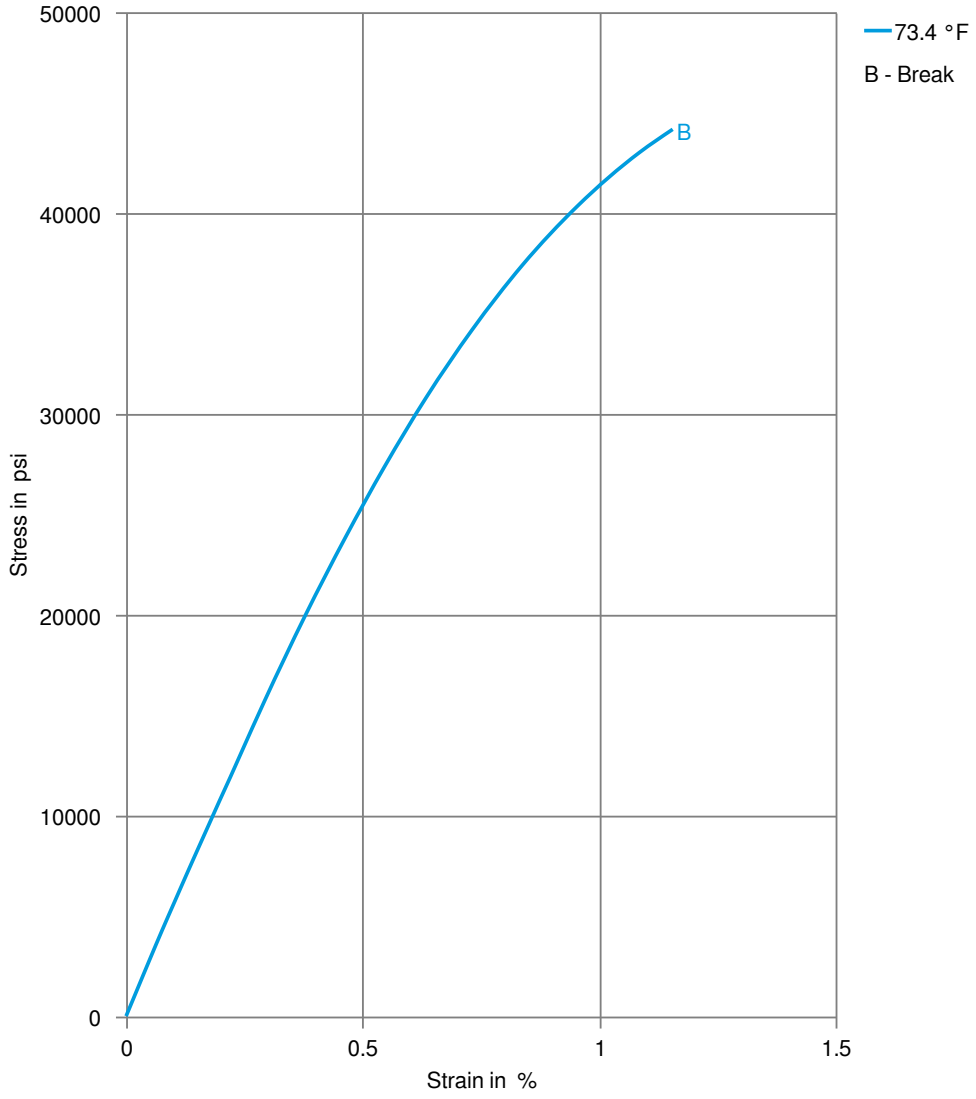
Additional information

Injection molding	During molding, use proper protective equipment and adequate ventilation. Avoid exposure to fumes and limit the hold up time and temperature of the resin in the machine. Purge degraded resin carefully with HDPE.

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Stress-strain (dry)



Revised: 2026-06-18 Source: Celanese Materials Database

The above data are preliminary and are subject to change as additional data are developed on subsequent lots.
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